MC74LCX244

Low-Voltage CMOS Octal Buffer

With 5 V–Tolerant Inputs and Outputs (3–State, Non–Inverting)

The MC74LCX244 is a high performance, non–inverting octal buffer operating from a 2.3 to 3.6 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A V_I specification of 5.5 V allows MC74LCX244 inputs to be safely driven from 5 V devices. The MC74LCX244 is suitable for memory address driving and all TTL level bus oriented transceiver applications.

Current drive capability is 24 mA at the outputs. The Output Enable ($\overline{OE}$) input, when HIGH, disables the output by placing them in a HIGH Z condition.
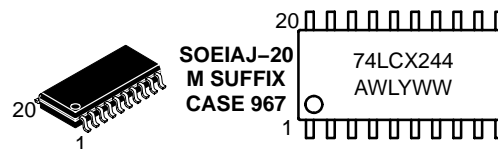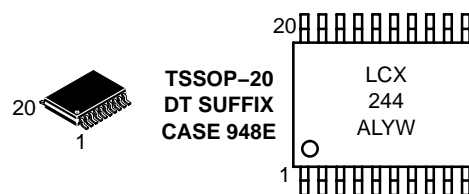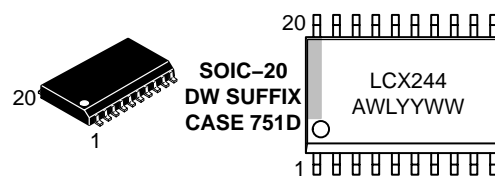
Features

- Designed for 2.3 to 3.6 V V_{CC} Operation
- 5 V Tolerant – Interface Capability With 5 V TTL Logic
- Supports Live Insertion and Withdrawal
- I_{OFF} Specification Guarantees High Impedance When $V_{CC} = 0$ V
- LVTTL Compatible
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current in All Three Logic States (10 µA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500 mA
- ESD Performance: Human Body Model >2000 V
                       Machine Model >200 V
- Pb–Free Packages are Available*

ON Semiconductor®

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MARKING DIAGRAMS

SOIC–20 DW SUFFIX CASE 751D	LCX244 AWLYYWW
TSSOP–20 DT SUFFIX CASE 948E	LCX 244 ALYW
SOEIAJ–20 M SUFFIX CASE 967	74LCX244 AWLYWW

A   = Assembly Location
L, WL = Wafer Lot
Y, YY = Year
W, WW = Work Week

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.
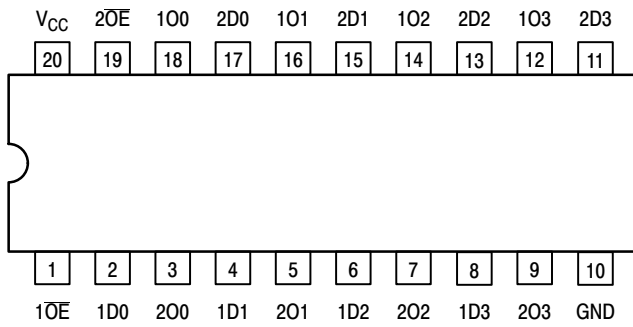
1

MC74LCX244

Figure 1. Pinout: 20–Lead (Top View)

V$_{CC}$ 20	

Top pins (left to right): V$_{CC}$ (20), 2$\overline{OE}$ (19), 1O0 (18), 2D0 (17), 1O1 (16), 2D1 (15), 1O2 (14), 2D2 (13), 1O3 (12), 2D3 (11)

Bottom pins (left to right): 1$\overline{OE}$ (1), 1D0 (2), 2O0 (3), 1D1 (4), 2O1 (5), 1D2 (6), 2O2 (7), 1D3 (8), 2O3 (9), GND (10)

PIN NAMES

PINS	FUNCTION
n$\overline{OE}$	Output Enable Inputs
1Dn, 2Dn	Data Inputs
1On, 2On	3–State Outputs

TRUTH TABLE

INPUTS		OUTPUTS
1$\overline{OE}$ 2$\overline{OE}$	1Dn 2Dn	1On, 2On
L	L	L
L	H	H
H	X	Z

H = High Voltage Level
L = Low Voltage Level
Z = High Impedance State
X = High or Low Voltage Level and Transitions are Acceptable
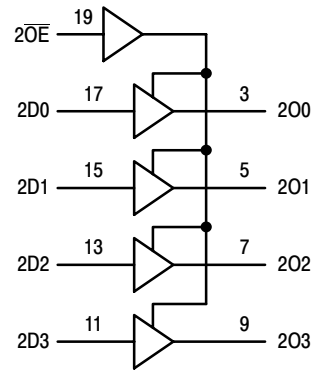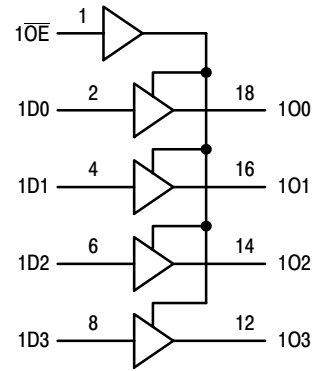For I$_{CC}$ reasons, DO NOT FLOAT Inputs

Figure 2. Logic Diagram

MC74LCX244

MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Unit
V_{CC}	DC Supply Voltage	−0.5 to +7.0		V
V_I	DC Input Voltage	$−0.5 \leq V_I \leq +7.0$		V
V_O	DC Output Voltage	$−0.5 \leq V_O \leq +7.0$	Output in 3−State	V
		$−0.5 \leq V_O \leq V_{CC} + 0.5$	Output in HIGH or LOW State (Note 1)	V
I_{IK}	DC Input Diode Current	−50	$V_I <$ GND	mA
I_{OK}	DC Output Diode Current	−50	$V_O <$ GND	mA
		+50	$V_O > V_{CC}$	mA
I_O	DC Output Source/Sink Current	±50		mA
I_{CC}	DC Supply Current Per Supply Pin	±100		mA
I_{GND}	DC Ground Current Per Ground Pin	±100		mA
T_{STG}	Storage Temperature Range	−65 to +150		°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.
1. I_O absolute maximum rating must be observed.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	Operating	2.0	2.5, 3.3	3.6	V
		Data Retention Only	1.5	2.5, 3.3	3.6	
V_I	Input Voltage		0		5.5	V
V_O	Output Voltage	(HIGH or LOW State)	0		V_{CC}	V
		(3−State)	0		5.5	
I_{OH}	HIGH Level Output Current	V_{CC} = 3.0 V − 3.6 V			−24	mA
		V_{CC} = 2.7 V − 3.0 V			−12	
I_{OL}	LOW Level Output Current	V_{CC} = 3.0 V − 3.6 V			24	mA
		V_{CC} = 2.7 V − 3.0 V			12	
T_A	Operating Free−Air Temperature		−40		+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate, V_{IN} from 0.8 V to 2.0 V, V_{CC} = 3.0 V		0		10	ns/V

ORDERING INFORMATION

Device	Package	Shipping†
MC74LCX244DW	SOIC−20	38 Units / Rail
MC74LCX244DWR2	SOIC−20	1000 Tape & Reel
MC74LCX244DR2G	SOIC−20 (Pb−Free)	1000 Tape & Reel
MC74LCX244DT	TSSOP−20*	75 Units / Rail
MC74LCX244DTR2	TSSOP−20*	2000 Tape & Reel
MC74LCX244MEL	SOEIAJ−20	2000 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*This package is inherently Pb−Free.

DC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic	Condition	T_A = −40°C to +85°C Min	Max	Unit
V_{IH}	HIGH Level Input Voltage (Note 2)	2.3 V ≤ V_{CC} ≤ 2.7 V	1.7		V
		2.7 V ≤ V_{CC} ≤ 3.6 V	2.0		
V_{IL}	LOW Level Input Voltage (Note 2)	2.3 V ≤ V_{CC} ≤ 2.7 V		0.7	V
		2.7 V ≤ V_{CC} ≤ 3.6 V		0.8	
V_{OH}	HIGH Level Output Voltage	2.3 V ≤ V_{CC} ≤ 3.6 V; I_{OL} = 100 μA	V_{CC} − 0.2		V
		V_{CC} = 2.3 V; I_{OH} = −8 mA	1.8		
		V_{CC} = 2.7 V; I_{OH} = −12 mA	2.2		
		V_{CC} = 3.0 V; I_{OH} = −18 mA	2.4		
		V_{CC} = 3.0 V; I_{OH} = −24 mA	2.2		
V_{OL}	LOW Level Output Voltage	2.3 V ≤ V_{CC} ≤ 3.6 V; I_{OL} = 100 μA		0.2	V
		V_{CC} = 2.3 V; I_{OL}= 8 mA		0.6	
		V_{CC} = 2.7 V; I_{OL}= 12 mA		0.4	
		V_{CC} = 3.0 V; I_{OL} = 16 mA		0.4	
		V_{CC} = 3.0 V; I_{OL} = 24 mA		0.55	
I_I	Input Leakage Current	2.3 V ≤ V_{CC} ≤ 3.6 V; 0 V ≤ V_I ≤ 5.5 V		±5	μA
I_{OZ}	3–State Output Current	2.3 ≤ V_{CC} ≤ 3.6 V; 0 V ≤ V_O ≤ 5.5 V; V_I = V_{IH} or V_{IL}		±5	μA
I_{OFF}	Power–Off Leakage Current	V_{CC} = 0 V; V_I or V_O = 5.5 V		10	μA
I_{CC}	Quiescent Supply Current	2.3 ≤ V_{CC} ≤ 3.6 V; V_I = GND or V_{CC}		10	μA
		2.3 ≤ V_{CC} ≤ 3.6 V; 3.6 ≤ V_I or V_O ≤ 5.5 V		±10	
ΔI_{CC}	Increase in I_{CC} per Input	2.3 ≤ V_{CC} ≤ 3.6 V; V_{IH} = V_{CC} − 0.6 V		500	μA

2. These values of V_I are used to test DC electrical characteristics only.

AC CHARACTERISTICS (t_R = t_F = 2.5 ns; R_L = 500 Ω)

			Limits						
			T_A = −40°C to +85°C						
			V_{CC} = 3.0 V to 3.6 V		V_{CC} = 2.7 V		V_{CC} = 2.5 V ±0.2		
			C_L = 50 pF		C_L = 50 pF		C_L = 30 pF		
Symbol	Parameter	Waveform	Min	Max	Min	Max	Min	Max	Unit
t_{PLH} t_{PHL}	Propagation Delay Input to Output	1	1.5 1.5	6.5 6.5	1.5 1.5	7.5 7.5	1.5 1.5	7.8 7.8	ns
t_{PZH} t_{PZL}	Output Enable Time to High and Low Level	2	1.5 1.5	8.0 8.0	1.5 1.5	9.0 9.0	1.5 1.5	10 10	ns
t_{PHZ} t_{PLZ}	Output Disable Time From High and Low Level	2	1.5 1.5	7.0 7.0	1.5 1.5	8.0 8.0	1.5 1.5	8.4 8.4	ns
t_{OSHL} t_{OSLH}	Output–to–Output Skew (Note 3)			1.0 1.0					ns

3. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH–to–LOW (t_{OSHL}) or LOW–to–HIGH (t_{OSLH}); parameter guaranteed by design.
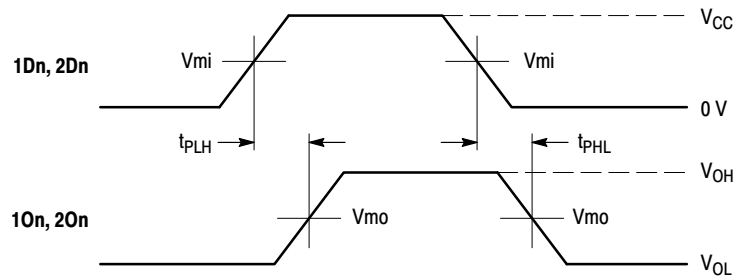
DYNAMIC SWITCHING CHARACTERISTICS

Symbol	Characteristic	Condition	$T_A = +25°C$			Unit
			Min	Typ	Max	
V_{OLP}	Dynamic LOW Peak Voltage (Note 4)	V_{CC} = 3.3 V, C_L = 50 pF, V_{IH} = 3.3 V, V_{IL} = 0 V V_{CC} = 2.5 V, C_L = 30 pF, V_{IH} = 2.5 V, V_{IL} = 0 V		0.8 0.6		V
V_{OLV}	Dynamic LOW Valley Voltage (Note 4)	V_{CC} = 3.3 V, C_L = 50 pF, V_{IH} = 3.3 V, V_{IL} = 0 V V_{CC} = 2.5 V, C_L = 30 pF, V_{IH} = 2.5 V, V_{IL} = 0 V		−0.8 −0.6		V

4. Number of outputs defined as "n". Measured with "n−1" outputs switching from HIGH–to–LOW or LOW–to–HIGH. The remaining output is measured in the LOW state.
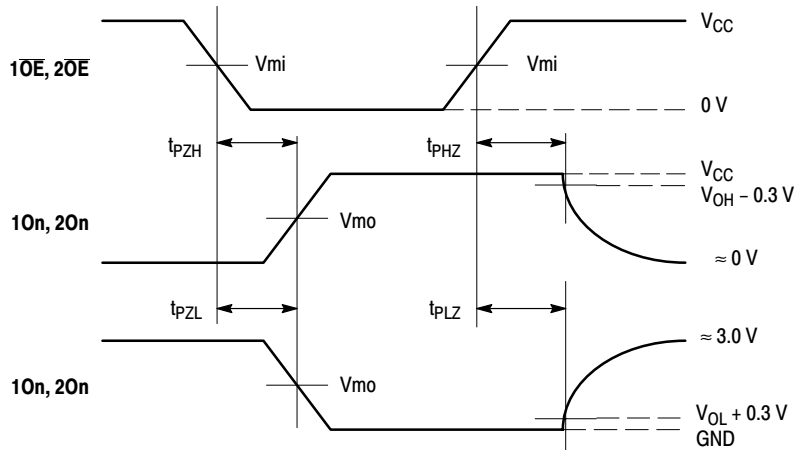
CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C_{IN}	Input Capacitance	V_{CC} = 3.3 V, V_I = 0 V or V_{CC}	7	pF
C_{OUT}	Output Capacitance	V_{CC} = 3.3 V, V_I = 0 V or V_{CC}	8	pF
C_{PD}	Power Dissipation Capacitance	10 MHz, V_{CC} = 3.3 V, V_I = 0 V or V_{CC}	25	pF

WAVEFORM 1 – PROPAGATION DELAYS
$t_R = t_F$ = 2.5 ns, 10% to 90%; f = 1 MHz; t_W = 500 ns

WAVEFORM 2 – OUTPUT ENABLE AND DISABLE TIMES
$t_R = t_F$ = 2.5 ns, 10% to 90%; f = 1 MHz; t_W = 500 ns

Figure 3. AC Waveforms

Symbol	V_{CC}		
	3.3 V ± 0.3 V	2.7 V	2.5 V ± 0.2 V
Vmi	1.5 V	1.5 V	$V_{CC}/2$
Vmo	1.5 V	1.5 V	$V_{CC}/2$
V_{HZ}	V_{OL} + 0.3 V	V_{OL} + 0.3 V	V_{OL} + 0.15 V
V_{LZ}	V_{OH} − 0.3 V	V_{OH} − 0.3 V	V_{OH} − 015 V

TEST	SWITCH
t_{PLH}, t_{PHL}	Open
t_{PZL}, t_{PLZ}	6 V at V_{CC} = 3.3 $\pm$0.3 V 6 V at V_{CC} = 2.5 $\pm$0.2 V
Open Collector/Drain t_{PLH} and t_{PHL}	6 V
t_{PZH}, t_{PHZ}	GND

C_L = 50 pF at V_{CC} = 3.3 $\pm$0.3 V or equivalent (includes jig and probe capacitance)
C_L = 30 pF at V_{CC} = 2.5 $\pm$0.2 V or equivalent (includes jig and probe capacitance)
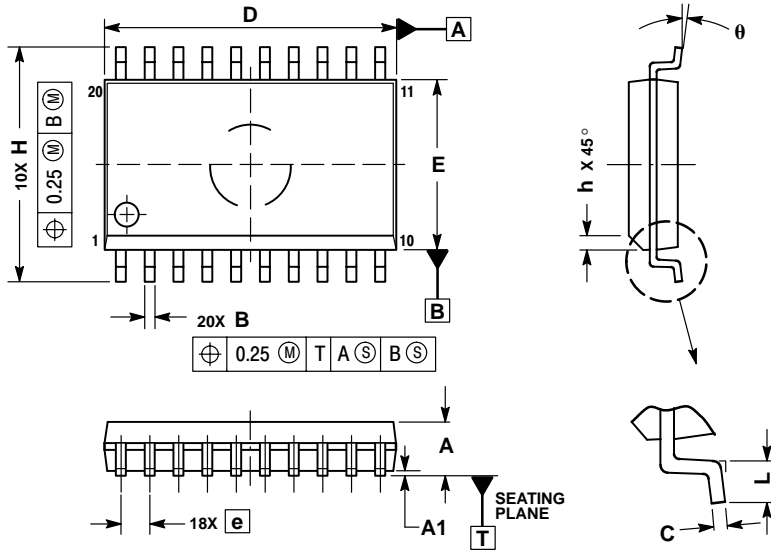R_L = R_1 = 500 Ω or equivalent
R_T = Z_{OUT} of pulse generator (typically 50 Ω)

Figure 4. Test Circuit

PACKAGE DIMENSIONS
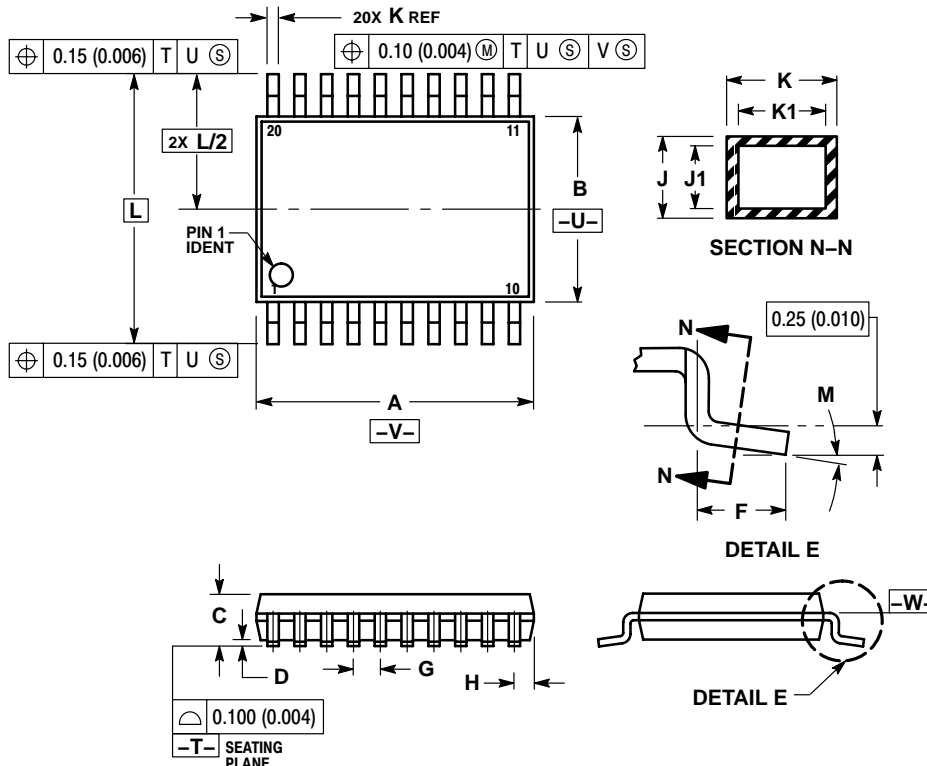
SOIC–20
DW SUFFIX
CASE 751D–05
ISSUE G

NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS	
	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
B	0.35	0.49
C	0.23	0.32
D	12.65	12.95
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
θ	0 °	7 °

TSSOP–20
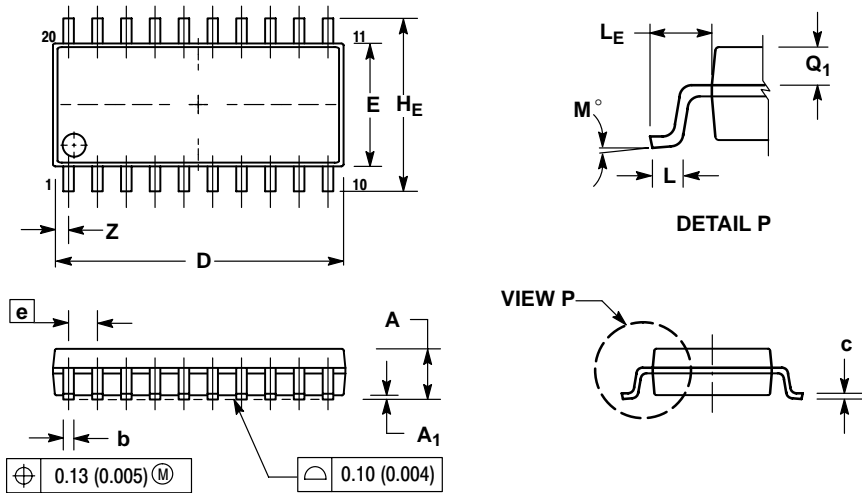**DT SUFFIX**
CASE 948E–02
ISSUE B

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.40	6.60	0.252	0.260
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0 °	8 °	0 °	8 °

MC74LCX244

PACKAGE DIMENSIONS

SOEIAJ–20
M SUFFIX
CASE 967–01
ISSUE O

DETAIL P

VIEW P

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	12.35	12.80	0.486	0.504
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H_E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L_E	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q₁	0.70	0.90	0.028	0.035
Z	---	0.81	---	0.032

[x]

◉ Part #/Keyword   ○ Cross-Reference » Advanced

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MC74LCX244: Low Voltage Octal Noninverting Buffer, 3 State

[x] Overview [x] [x] Specifications [x]

»View Reliability Data
Datasheet: Low Voltage CMOS Octal Buffer   »View Material Composition

Product Description

The MC74LCX244 is a high performance, non-inverting octal buffer operating from a 2.3 to 3.6V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A V_I specification of 5.5V allows MC74LCX244 inputs to be safely driven from 5V devices. The MC74LCX244 is suitable for memory address driving and all TTL level bus oriented transceiver applications.

Current drive capability is 24mA at the outputs. The Output Enable (OEbar) input, when HIGH, disables the output by placing them in a HIGH Z condition.

Features

- Designed for 2.3 to 3.6V V_{CC} Operation
- 5V Tolerant - Interface Capability With 5V TTL Logic
- Supports Live Insertion and Withdrawal
- I_{OFF} Specification Guarantees High Impedance When V_{CC} = 0V
- LVTTL Compatible
- LVCMOS Compatible
- 24mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current in All Three Logic States (10μA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500mA
- ESD Performance: Human Body Model >2000V; Machine Model >200V
- Pb-Free Packages are Available*

Technical Information

Simulation Models (3)   Package Drawings (4)
Data Sheets (1)

Availability and Samples

Product	New	Pb-free	Description	Status	Package Type	Pins	Case Outline	MSL*	Container Type	Qty.	Budgetary Price/Unit
MC74LCX244DT			Low Voltage Octal Noninverting Buffer, 3 State	Active, Not Rec	TSSOP 20 LEAD	20	948E-02	1	Rail	75	$0.2667
MC74LCX244DTG			Low Voltage Octal Noninverting Buffer, 3 State	Active	TSSOP 20 LEAD	20	948E-02	1	Rail	75	$0.2667 Order Samples Inventory
MC74LCX244DTR2			Low Voltage Octal Noninverting Buffer, 3 State	Active, Not Rec	TSSOP 20 LEAD	20	948E-02	1	Tape and Reel	2500	$0.2667 Inventory

Part	Description	Status	Package	Pins	Document	MSL	Packaging	Qty	Price / Inventory
MC74LCX244DTR2G	Low Voltage Octal Noninverting Active Buffer, 3 State		TSSOP 20 LEAD	20	948E-02	1	Tape and Reel	2500	$0.2667 Order Samples Inventory
MC74LCX244DWG	Low Voltage Octal Noninverting Active Buffer, 3 State		SOIC-20 WB	20	751D-05	3	Tube	38	$0.2933 Order Samples Inventory
MC74LCX244DWR2G	Low Voltage Octal Noninverting Active Buffer, 3 State		SOIC-20 WB	20	751D-05	3	Tape and Reel	1000	$0.2933 Order Samples Inventory
MC74LCX244MELG	Low Voltage Octal Noninverting Active Buffer, 3 State		SOEIAJ-20	20	967-01	3	Tape and Reel	2000	$0.3333 Order Samples Inventory
MC74LCX244DW	Low Voltage Octal Noninverting Active Buffer, 3 State		SOIC-20 WB	20	751D-05	1	Rail	38	$0.2933 Inventory
MC74LCX244DWR2	Low Voltage Octal Noninverting Active Buffer, 3 State		SOIC-20 WB	20	751D-05	1	Tape and Reel	1000	$0.2933 Inventory
MC74LCX244M	Low Voltage Octal Noninverting Active Buffer, 3 State	Last Shipments	SOEIAJ-20	20	967-01	3	Rail	40	Rochester Contact Sales Office
MC74LCX244MEL	Low Voltage Octal Noninverting Active Buffer, 3 State	Last Shipments	SOEIAJ-20	20	967-01	3	Tape and Reel	2000	Rochester Contact Sales Office

Moisture Sensitivity level (MSL) for surface mount devices (lead free measured at 260°C reflow, non lead free at 235°C reflow)

I_O Max (mA) : 24

Channels : 8

V_{CC} Max (V) : 3.6

: 6.5

t_{pd} Max (ns)

V_{CC} Min (V) : 2

Package : TSSOP 20 LEAD

Output : 3-State

Market Leadtime (weeks) : 2 to 4

ON Semiconductor (2007-01-20) : 2025

Channels : 8

I_O Max (mA) : 24

V_{CC} Max (V) : 3.6

t_{pd} Max (ns) : 6.5

V_{CC} Min (V) : 2

Output : 3-State

Package : TSSOP 20 LEAD

Market Leadtime (weeks) : 2 to 4

Arrow (2007-01-23) : In Stock

Avnet (2007-01-23) : >1K

I_O Max (mA) : 24

Channels : 8

V_{CC} Max (V) : 3.6

t_{pd} Max (ns) : 6.5

V_{CC} Min (V) : 2

Package : TSSOP 20 LEAD

Output : 3-State

Market Leadtime (weeks) : 2 to 4

Digi-Key (2007-01-23) : >1K

ON Semiconductor (2007-01-20) : 52500

Channels : 8

I_O Max (mA) : 24

V_{CC} Max (V) : 3.6

t_{pd} Max (ns) : 6.5

V_{CC} Min (V) : 2

Package : TSSOP 20 LEAD

Output : 3-State

Market Leadtime (weeks) : 2 to 4

Arrow (2007-01-23) : In Stock

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Avnet (2007-01-23) : >1K
Digi-Key (2007-01-23) : >1K
Future Electronics (2007-01-23) : In Stock
ON Semiconductor (2007-01-20) : 277356
P&S (2007-01-23) : >1K

Channels : 8
I_O Max (mA) : 24
V_{CC} Max (V) : 3.6
t_{pd} Max (ns) : 6.5
V_{CC} Min (V) : 2
Output : 3-State
Package : SOIC-20 WB
Market Leadtime (weeks) : 2 to 4

Arrow (2007-01-23) : In Stock
Avnet (2007-01-23) : >1K
ON Semiconductor (2007-01-20) : 6498
I_O Max (mA) : 24
Channels : 8
V_{CC} Max (V) : 3.6
t_{pd} Max (ns) : 6.5
V_{CC} Min (V) : 2
Output : 3-State
Package : SOIC-20 WB
Market Leadtime (weeks) : 4 to 8

Digi-Key (2007-01-23) : >1K
Future Electronics (2007-01-23) : In Stock
ON Semiconductor (2007-01-20) : 1000
Channels : 8
I_O Max (mA) : 24
V_{CC} Max (V) : 3.6
t_{pd} Max (ns) : 6.5
V_{CC} Min (V) : 2
Package : SOEIAJ-20
Output : 3-State
Market Leadtime (weeks) : 4 to 8
Digi-Key (2007-01-23) : >1K

ON Semiconductor (2007-01-20) : 4000

I_O Max (mA) : 24

Channels : 8

V_{CC} Max (V) : 3.6

t_{pd} Max (ns) : 6.5

V_{CC} Min (V) : 2

Package : SOIC-20 WB

Output : 3-State

Market Leadtime (weeks) : 2 to 4

Arrow (2007-01-23) : In Stock

Avnet (2007-01-23) : <1K

ON Semiconductor (2007-01-20) : 5244

I_O Max (mA) : 24

Channels : 8

V_{CC} Max (V) : 3.6

t_{pd} Max (ns) : 6.5

V_{CC} Min (V) : 2

Output : 3-State

Package : SOIC-20 WB

Market Leadtime (weeks) : 4 to 8

Future Electronics (2007-01-23) : In Stock

I_O Max (mA) : 24

Channels : 8

V_{CC} Max (V) : 3.6

t_{pd} Max (ns) : 6.5

V_{CC} Min (V) : 2

Package : SOEIAJ-20

Output : 3-State

Market Leadtime (weeks) : 12+

I_O Max (mA) : 24

Channels : 8

V_{CC} Max (V) : 3.6

t_{pd} Max (ns) : 6.5

V_{CC} Min (V) : 2

Package : SOEIAJ-20

Output   : 3-State

Market Leadtime (weeks)   : 12+

ON Semiconductor (2007-01-20) : 12000

Selected Electrical Specifications

For full electrical specifications, see the datasheet.

Symbol	Boundary	Value	Unit	Condition
V_{CC}	min	2	V	
V_{CC}	max	3.6	V	
t_{pd}	max	6.5	ns	Input to Output, T_A = 25 degrees C, C_L = 50 pF, V_{CC} = 3.3 Volts
I_O	max	24	mA	V_{CC} = 3 Volts
Output		3-State		
Channels		8		

For complete packaging information, see the datasheet

»View Material Composition

Case Outlines

948E-02   751D-05   967-01   940C-03